

REMARKS

Claims 1-5 and 10-11 are pending in the application.

Claim 4 is allowed.

Claims 1, 3, and 10 are rejected.

Claim 2 is objected to.

Claim 1 is rejected under 35 U.S.C. 102(e).

Claims 3 and 10 are rejected under 35 U.S.C. 103(a).

Claims 1 and 4 are currently amended.

Claim 11 is new.

No new matter is added.

Claims 1-5 and 10 remain in the case for consideration.

Applicant requests reconsideration and allowance of the claims in light of the above amendments and following remarks.

Specification

Claims 1-3 and 10 are objected to because of the following informalities: in claim 1, line 3, add --of-- between "the circuit region" and "a substrate".

Claim 1 has been amended to correct this clerical error.

Claim Rejections - 35 USC § 102

Claim 1 is rejected under 35 U.S.C. 102(e) as being anticipated by Hung et al. (US 2003/0020163 A1).

Applicants respectfully traverse this rejection.

Claim 1 recites multi-layer wirings interposed in the insulating film of the pad region and interposed in the low-k dielectric film of the circuit region.

Hung does not teach or anticipate this limitation of claim 1 as amended hereby. The Examiner points out apparent multi-layer wirings, for example 202, 208, and 214 on the insulating film 230 of the pad region and the low-k dielectric film of the circuit region. However, there are no multi-layer wirings interposed in the insulating film 230, not to mention "the insulating film interposed in the low-k dielectric film of the pad region," as recited in amended claim 1. See, for example, FIG. 2C of Hung, in which the multi-layer wirings 202, 208, and 214 are not *interposed* in the insulating film 230. Furthermore, the disparity between Hung's insulation film 230 and the insulation film recited in claim 1 is

quite apparent when comparing FIG. 2 of the instant application and FIG. 2C of Hung, as follows. In an apparent pad region, Hung shows only a single passivation layer (insulation film) that is above all of the dielectric film layers and multi-layer wirings. For at least these reasons, Hung does not anticipate claim 1, and applicants request withdrawal of the rejection for this claim.

Claim 1 has been amended, as explained above, to more accurately describe the claimed invention, and not necessarily to overcome the reference Hung. Indeed, applicants believe that claim 1, before the current amendment, is not anticipated by Hung for at least the following reason: There are no multi-layer wirings on the insulating film 230. Referring to FIG. 2C, for example, the multi-layer wirings 202, 208, and 214 are BELOW the insulating film 230, certainly not ON the insulating film 230.

Support for the current amendments can be found, among other locations, in the Specification, page 3, lines 26-27 and 30-32.

Claim Rejections - 35 USC § 103

Claims 3 and 10 are rejected under 35 U.S.C. 103(a) as being unpatentable over Hung et al. (US 2003/0020163 A1).

Claims 3 and 10 are dependent on base claim 1; and therefore are allowable based on at least the allowability of claim 1. Withdrawal of the rejections for these claims is thus requested.

Allowable Subject Matter

Claim 2 is objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

Claims 4 and 5 are allowed.

Note that claim 4 has been amended to correct typographical errors, e.g., replacing "on" with "in." Support for the limitations can be found in, for example, FIG. 2 and the accompanying text.

Conclusion

For the foregoing reasons, reconsideration and allowance of claims 1-5 and 10-11 of the application as amended is solicited. The Examiner is encouraged to telephone the undersigned at (503) 222-3613 if it appears that an interview would be helpful in advancing the case.

Respectfully submitted,

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